



SSC8LA28GT4

N-Channel Enhancement Mode MOSFET

➤ Features

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D
120V	$\pm 20V$	$7.0m\Omega @ 10V$	102A

➤ Description

This device is N-Channel enhancement MOSFET. Uses SGT technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

100% UIS + ΔV_{DS} + R_g Tested!

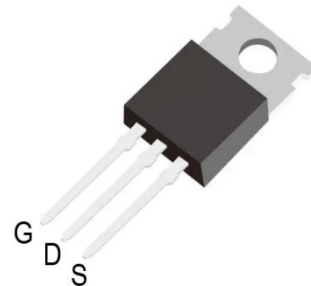
➤ Applications

- Load Switch
- PWM Application
- Power Management
- DC-DC Conversion

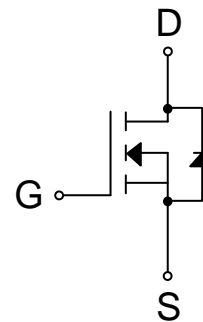
➤ Ordering Information

Device	Package	Shipping
SSC8LA28GT4	TO-220-3L	50/Tube

➤ Pin configuration



TO-220-3L (Top View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)

**➤ Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter		Ratings	Unit
V_{DS}	Drain-to-Source Voltage		120	V
V_{GS}	Gate-to-Source Voltage		± 20	V
I_D	Continuous Drain Current ^d	$T_C=25^{\circ}\text{C}$	102	A
		$T_C=100^{\circ}\text{C}$	56	
I_{DSM}	Continuous Drain Current ^a	$T_A=25^{\circ}\text{C}$	14	A
		$T_A=70^{\circ}\text{C}$	10	
I_{DM}	Pulsed Drain Current ^b		408	A
P_D	Power Dissipation ^c	$T_C=25^{\circ}\text{C}$	116	W
		$T_C=100^{\circ}\text{C}$	46	
P_{DSM}	Power Dissipation ^a	$T_A=25^{\circ}\text{C}$	2.5	W
		$T_A=70^{\circ}\text{C}$	1.6	
I_{AS}	Avalanche Current ^b $L=0.5\text{mH}$ Single Pulse		36	A
E_{AS}	Avalanche Energy ^b $L=0.5\text{mH}$ Single Pulse		324	mJ
T_J	Operation junction temperature		-55~150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range		-55~150	

➤ Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Type	Max.	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	50	65	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	1.07	1.5	

Note:

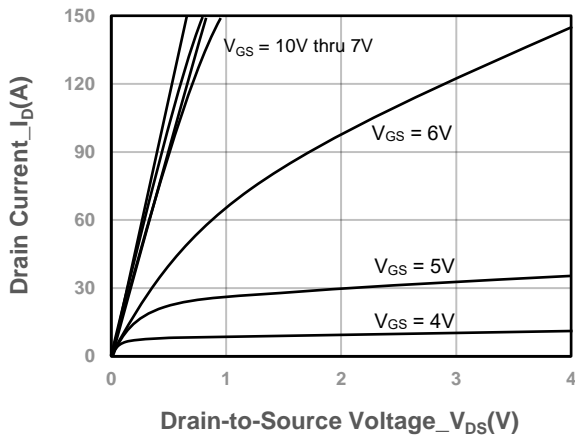
- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user is specific board design. The power dissipation is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_D is based on $T_{J(MAX)}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.

**➤ Electrical Characteristics (T_A=25°C unless otherwise noted)**

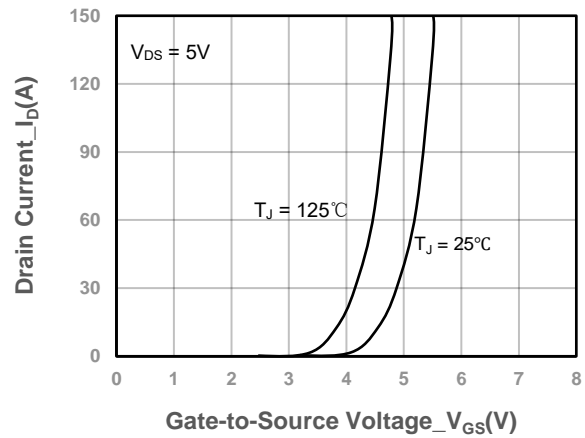
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	120			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	2.5	3.5	4.5	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 20A		7.0	10	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 120V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Transconductance	G _{FS}	V _{DS} = 5V, I _D = 15A		40		S
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 20A		0.8	1.3	V
Gate Resistance	R _G	V _{DS} = 0V, f = 1MHz		1.2		Ω
Input Capacitance	C _{ISS}	V _{DS} = 60V, V _{GS} = 0V, f = 1MHz		3700		pF
Output Capacitance	C _{OSS}			285		
Reverse Transfer Capacitance	C _{RSS}			25		
Total Gate Charge	Q _G	V _{GS} = 10V, V _{DS} = 60V, I _D = 20A		60		nC
Gate to Source Charge	Q _{GS}			24		
Gate to Drain Charge	Q _{GD}			16		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = 10V, V _{DS} = 60V, I _D = 20A, R _G = 3Ω,		22		ns
Rise Time	T _r			18		
Turn-off Delay Time	T _{D(OFF)}			48		
Fall Time	T _f			14		
Diode Recovery Time	T _{rr}	I _F =20A, di/dt=500A/us		68		ns
Diode Recovery Charge	Q _{rr}	I _F =20A, di/dt=500A/us		110		nC



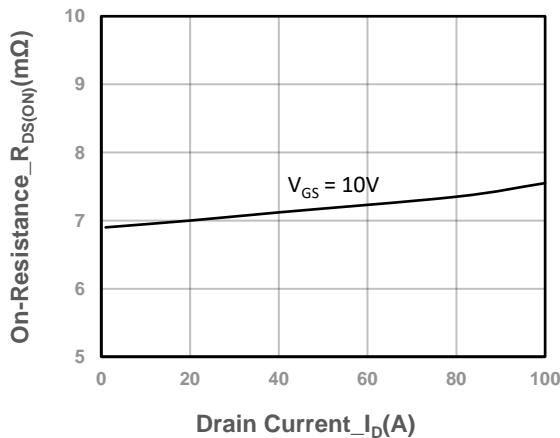
➤ Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



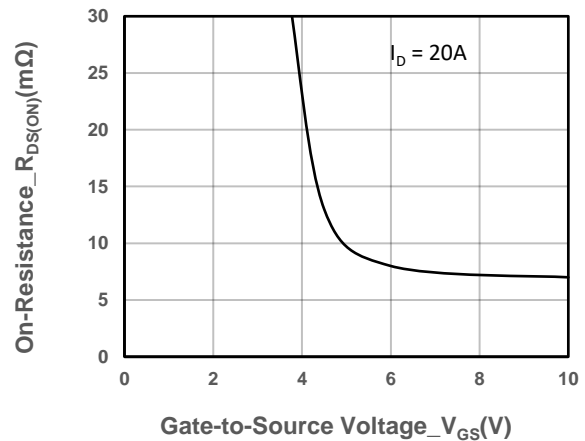
Output Characteristics



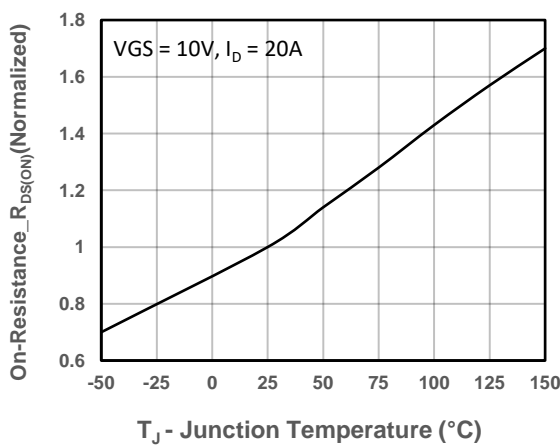
Transfer Characteristics



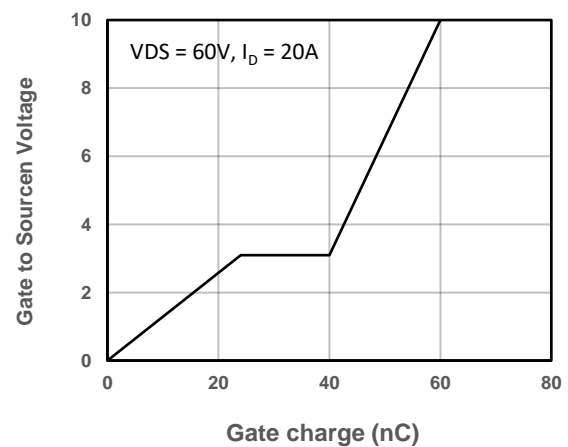
On-Resistance vs. Drain Current and Gate Voltg



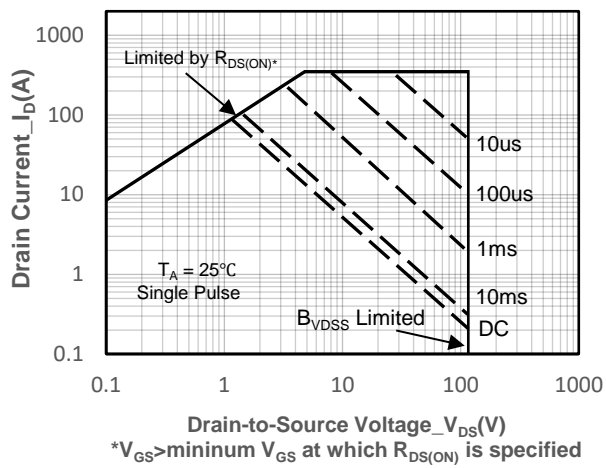
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature



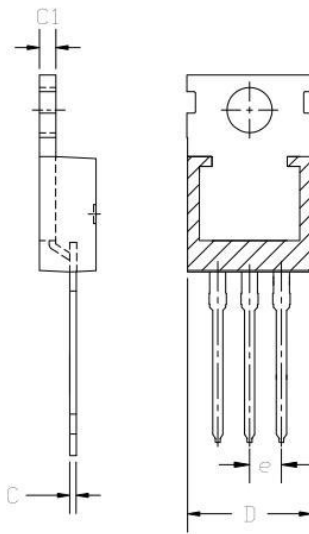
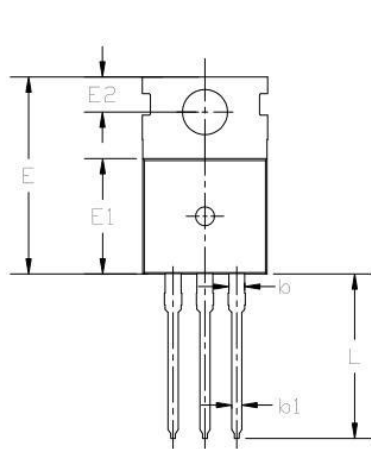
Gate-Source Voltage vs. Gate charge



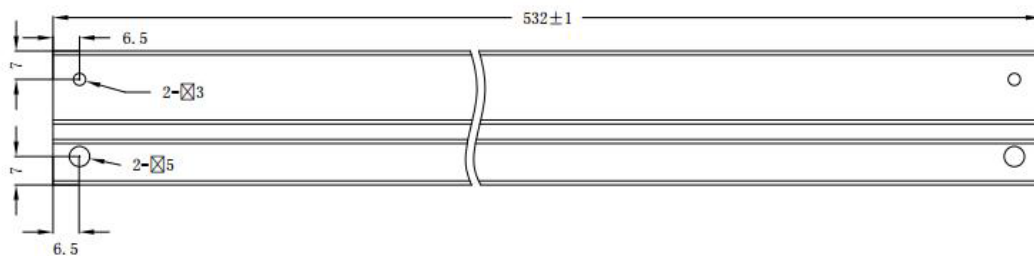
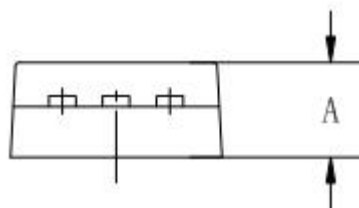
Safe Operating Area vs. Junction-to-Ambient



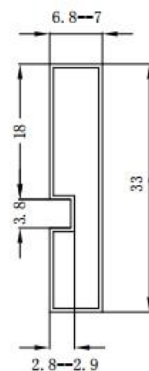
➤ Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.40	--	4.60
b	1.20	--	1.36
b1	0.70	--	0.90
C	0.48	--	0.53
C1	1.28	--	1.32
D	9.80	10.00	10.20
E	15.20	15.45	15.75
E1	9.00	9.20	9.40
E2	2.60	--	2.90
e	--	2.54	--
L	13.00	--	13.40



$$T=0.5 \pm 0.1$$



技术要求:

1. 材料: 透明PVC
2. 表面电阻: $10E5 \sim 10E10$ OHMS/SQ
3. 未注尺寸公差 ± 0.3
4. 黑色钉子由厂家出货时塞于左端



DISCLAIMER

SSCSEMI RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. SSCSEMI DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENCE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

THE GRAPHS PROVIDED IN THIS DOCUMENT ARE STATISTICAL SUMMARIES BASED ON A LIMITED NUMBER OF SAMPLES AND ARE PROVIDED FOR INFORMATIONAL PURPOSE ONLY. THE PERFORMANCE CHARACTERISTICS LISTED IN THEM ARE NOT TESTED OR GUARANTEED. IN SOME GRAPHS, THE DATA PRESENTED MAY BE OUTSIDE THE SPECIFIED OPERATING RANGE (E.G. OUTSIDE SPECIFIED POWER SUPPLY RANGE) AND THEREFORE OUTSIDE THE WARRANTED RANGE.

OUR PRODUCT SPECIFICATIONS ARE ONLY VALID IF OBTAINED THROUGH THE COMPANY'S OFFICIAL WEBSITE, CRM SYSTEM, OR OUR SALES PERSONNEL CHANNELS. IF CHANGES OR SPECIAL VERSIONS ARE INVOLVED, THEY MUST BE STAMPED WITH A QUALITY SEAL AND MARKED WITH A SPECIAL VERSION NUMBER TO BE VALID.